

Reply to Office Action dated July 29, 2004
Application Serial No. 10/038,264
Supplemental Amendment dated March 24, 2005

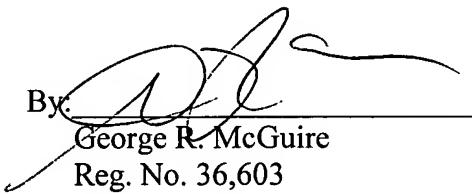
Remarks/Arguments

The present amendment is made in further response to the Office Action dated July 29, 2004, identified as Paper No. 20040719 the amendment filed November 29, 2004, and the notice of non-compliant amendment dated March 3, 2005, identified as Paper No. 20050225. Claims 17-24 are pending in the application

Applicant has added additional claim 24, specifically directed toward the elected species. As explained in the Amendment dated November 29, 2004, the cited art does not disclose the generically claimed solder joint. In particular, the references do not disclose the serpentine undulations on the metallic pad of a substrate for forming a solder joint with the serpentine undulations of the metallic pad of an electronic chip added in new claim 24.

In view of the foregoing amendments, the Examiner's reconsideration and allowance of the present application is believed to be in order. If the Examiner believes a phone conference with Applicant's attorney would expedite prosecution of this application, please contact the undersigned at (315) 218-8515.

Respectfully submitted,

By: 
George R. McGuire
Reg. No. 36,603

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BOND, SCHOENECK & KING, PLLC
One Lincoln Center
Syracuse, New York 13202-8530
(315)218-8515